

**YTLA-0020-2.0A****Features:****Frequency: DC~20GHz****Small Signal : 18dB****Noise Figure:2.0dB typ./3.5dB max.****P-1dB: 16dBm****Supplying:+8V/80mA****PI.PO.:50Ohm****Size: 3.3 x 1.3 x 0.1mm****Description:**

**YTLA-0220-2.0 is a wideband low noise distributed amplifier with frequency cover from 2-20GHz!This model has double power supplying with +8V and +0.65V with no Power on time sequence requirements!**

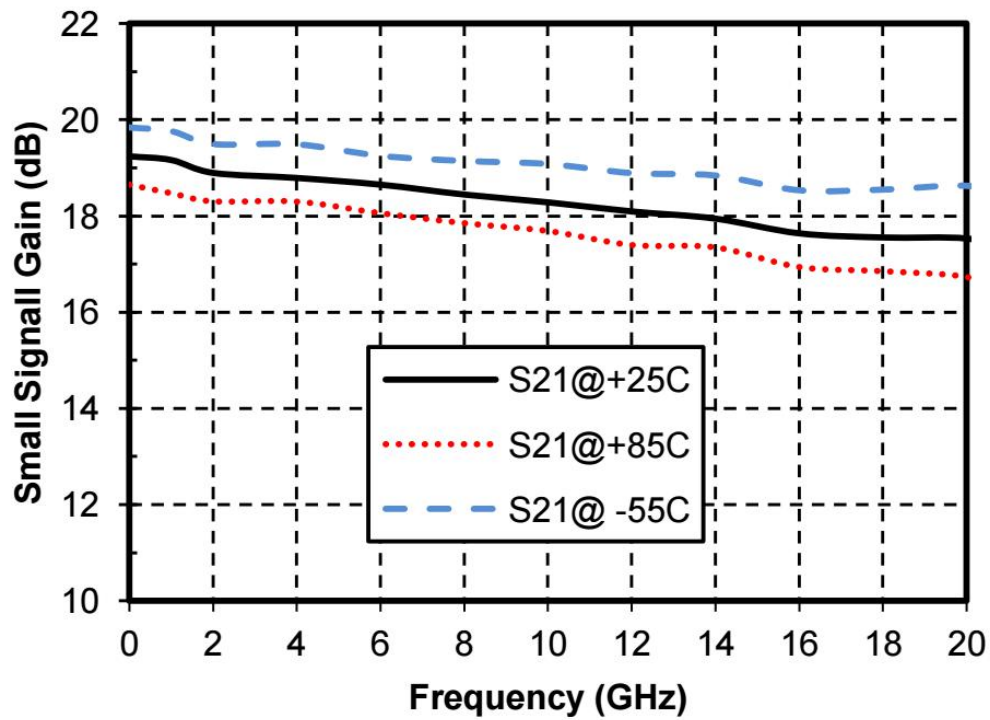
Limited Parameter	
Max Drain Voltage	12V
Max Input Power	+18dBm
Working Temperature	-55 ~ +85° C
Storage Temperature	-65 ~ +150° C

Features	Min	Typical	Max	Unite
Frequency	DC-20G			GHz
Small Singal Grain	17.5	18	19	dB

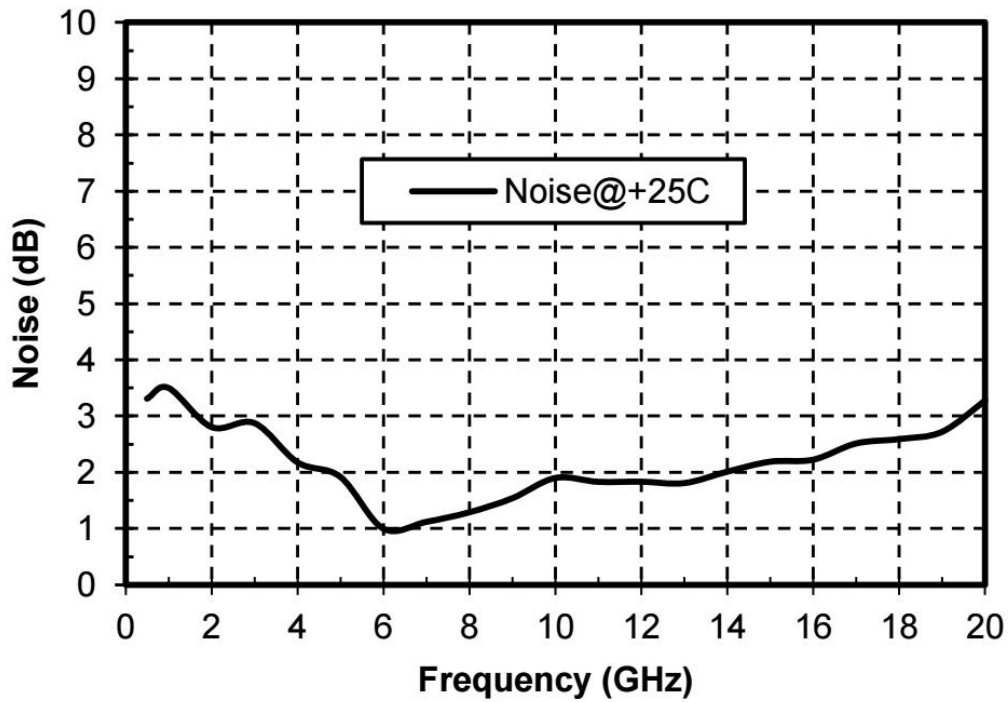


Flatness		$\pm 0.75$		dB
Noise Figure	-	2.0	3.5	dB
P-1dB	15.5	16	17	dBm
Input Return Loss		22		dB
Output Return Loss		20		dB
Static Current		80		mA

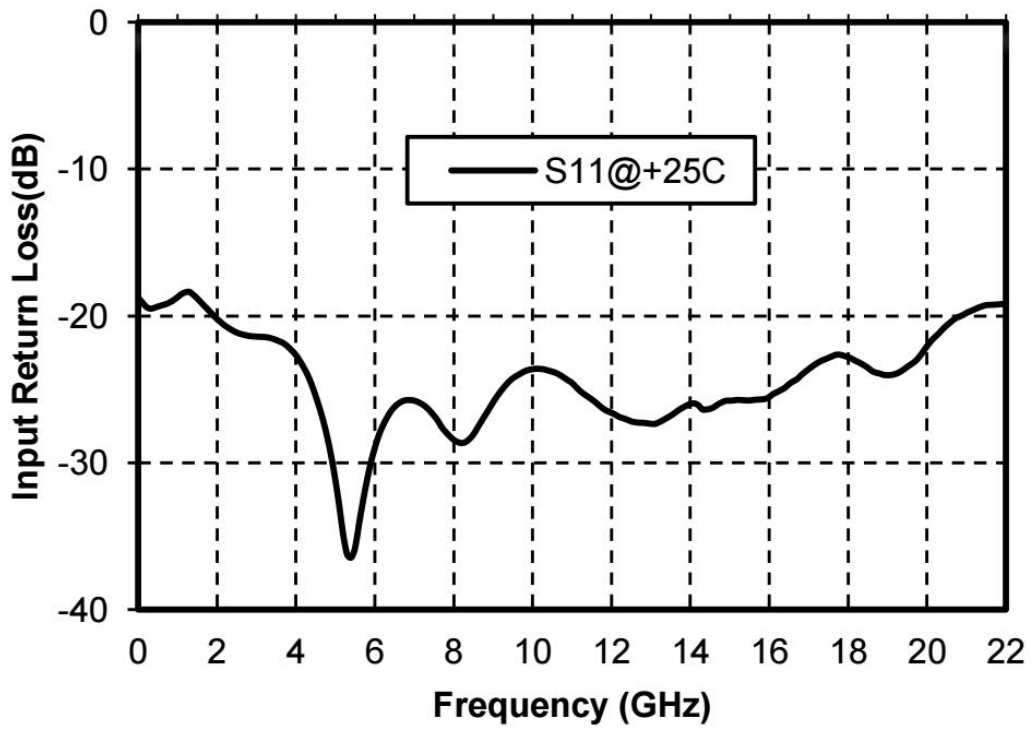
### Gain VS Temperature



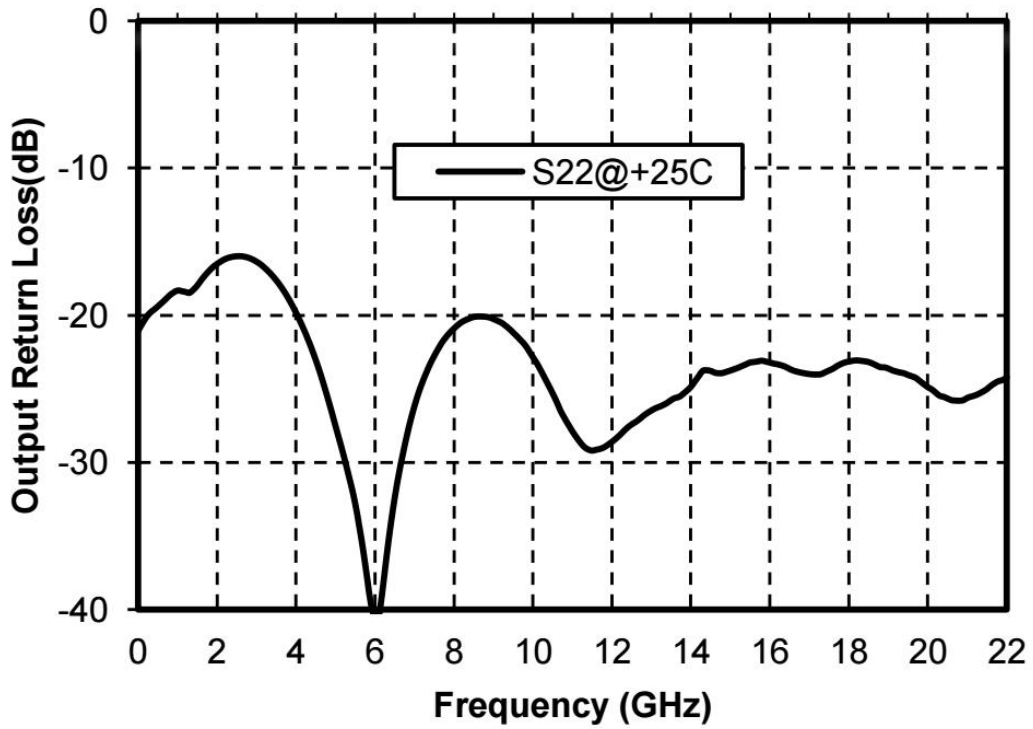
### Noise Figure VS Frequency



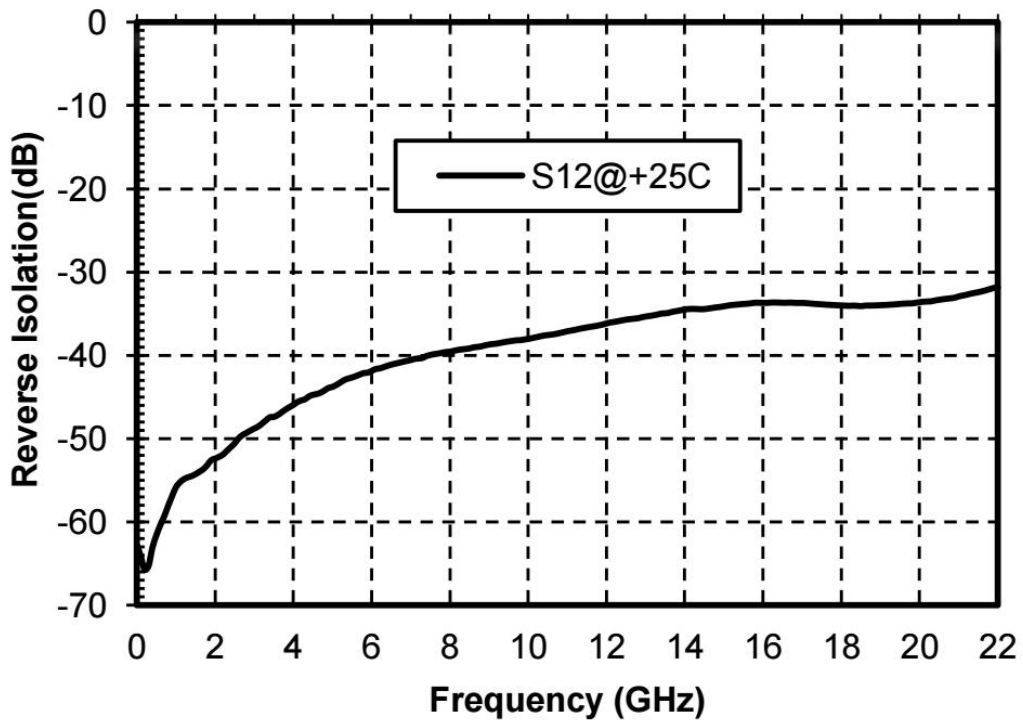
Input Return Loss VS Frequency



Output Return Loss VS Frequency

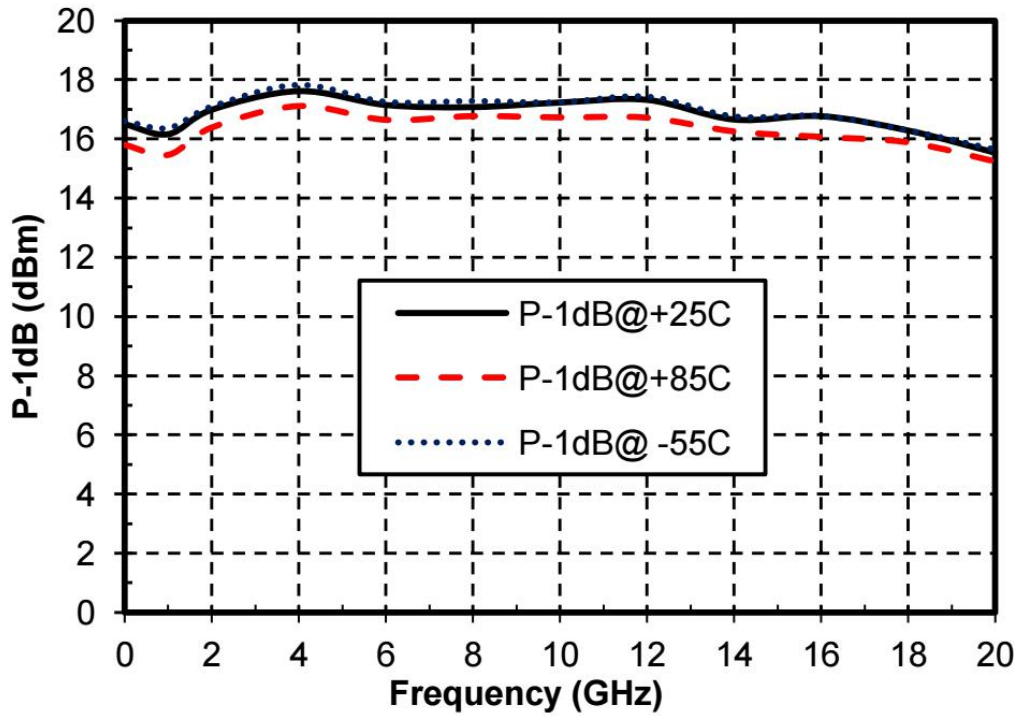


### Reverse Isolation VS Frequency





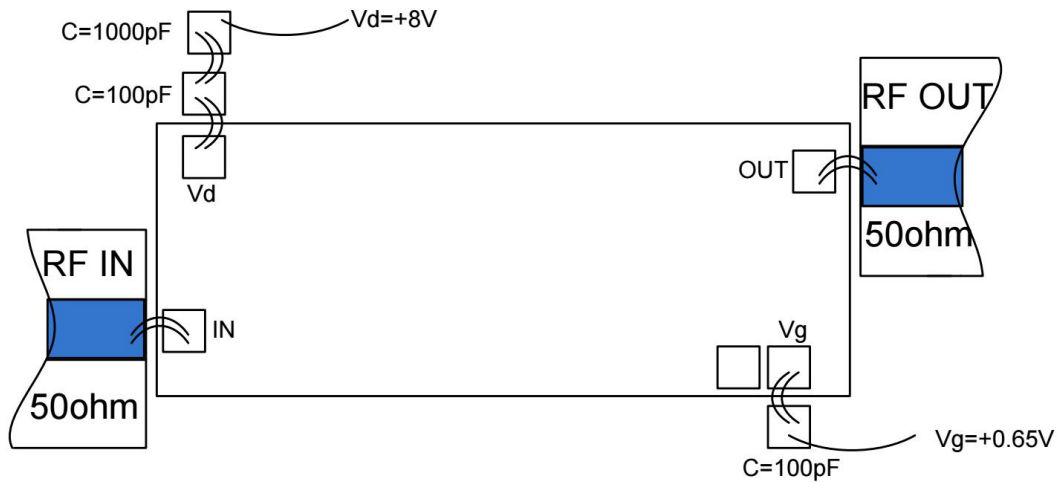
### P-1dB VS Temperature



### Outline Drawing:( $\mu$ m)



### Assembly Diagram:



### Handling Precautions

1. All bare die are placed in either Waffle or Gel based ESD protective containers, all die should be stored in a dry nitrogen environment.
2. Cleanliness: Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems
3. Follow ESD precautions to protect against ESD strikes  
Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers. The surface of the chip has fragile air bridges and should not be touched with vacuum collet, tweezers, or fingers
4. Eutectic Die Attach: A 80/20 gold tin preform is recommended with a work surface temperature of 255 ° C and a tool temperature of 265 ° C. When hot 90/10 nitrogen/hydrogen gas is applied, tool tip temperature should